Date: 2018. 6. 29

Data sheet

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE

ANTI-SULFURATION

Style: RMGW06,10,16,20,32,35,50,63

AEC-Q200 qualified

RoHS COMPLIANCE ITEM Halogen and Antimony Free

Note: • Stock conditions

Temperature: $+5^{\circ}\text{C} \sim +35^{\circ}\text{C}$ Relative humidity: $25\% \sim 75\%$

The period of guarantee: Within 2 year from shipmen t by the company.

Solderability shall be satisfied.

- Product specification contained in this data sheet are subject to change at any time without notice
- •If you have any questions or a Purchasing Specification for any quality Agreement is necessary, please contact our sales staff.



Hokkaido Research Center Approval by: T. Sannomiya Drawing by: M. Shibuya No: RMGW-K-HTS-0001

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Style

FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE **ANTI-SULFURATION** RMGW06,10,16,20,32,35,50,63

1. Scope

1.1 This data sheet covers the detail requirements for fixed thick film chip resistors; rectangular type & anti-sulfuration,, style of RMGW06,10,16,20,32,35,50,63.

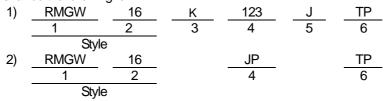
1.2 Applicable documents

JIS C 5201-1: 2011, JIS C 5201-8: 2014, JIS C 5201-8-1: 2014 IEC60115-1: 2008, IEC60115-8: 2009, IEC60115-8-1: 2014 EIAJ RC-2134C-2010

2. Classification

Type designation shall be the following form.

(Example)



- 1 Fixed thick film chip resistors; rectangular type & anti-sulfuration
- 2 Rated dissipation and / or dimension
- 3 Temperature coefficient of resistance

K	±100×10 ⁻⁶ / °C
-(Dash)	Standard

4 Rated resistance

123	E24 Series, 3 digit,	Ex. 123> 12kΩ,
1000	E96 Series, 4 digit,	Ex. 1000>100Ω
	_	1022> 10.2kΩ
JP	Chip jumper	

5 Tolerance on rated resistance

D	±0.5%
F	±1%
J	±5%

6 Packaging form

В	Bulk (loose package)
PA	Press pocket taping
TH	Paner tening
TP	Paper taping
TE	Embossed taping

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3. Rating

The ratings shall be in accordance with Table-1.

3.1 Resistor

Table-1(1)

Iable–1(1) Rated Table Afficient of Detail registers Preferred Tables on the						
Style	dissipation (W)		ure coefficient of nce (10°/°C)	Rated resistance range (Ω)	number series for resistors	Tolerance on rated resistance
,			+600~-200	1~3.92		
		Standard	+350~-100	4.02~9.76	E24, 96	F(±1%), J(±5%)
		•	±200	10~1M		
RMGW06	0.05		+600~200	1~3.92		
		Standard	+350~-100	4.02~9.76	E24	F(±1%), J(±5%)
		0.0	±200	10~1M		. (=170), 3(=370)
		K	±100	10~1M		
			±200	1.02M~10M	E24, 96	D(±1%), F(±1%)
		Standard	+500~-200	1~9.76	,,	F(±1%)
RMGW10	0.1	K	±100	10~1M		(,
		Standard	±200	1.1M~10M	E24	J(±5%)
		Standard	+500~-200	1.0~9.1		, ,
		K	±100	10~1M		D(±1%), F(±1%)
		Standard -	±200	1.02M~10M	E24, 96	
RMGW16 0.1		+500~-200	1~9.76		F(±1%)	
	K	±100	10~1M			
		Standard	±200	1.1M~10M	E24	J(±5%)
			+500~-200	1.0~9.1		
		K	±100	10~1M		D(±1%), F(±1%)
		Standard -	±200	1.02M~10M	E24, 96	D(±170),1 (±170)
RMGW20	0.125		+500~-200	1~9.76		F(±1%)
TAVIOVV20	0.125	K	±100	10~1M	-	
		Standard	±200	1.1M~10M	E24	J(±5%)
			+500~-200	1.0~9.1		
		K	±100	10~1M	-	D(±1%), F(±1%)
		Standard	±200	1.02M~10M	E24, 96	. , , , ,
RMGW32	0.25		+500~-200	1~9.76		F(±1%)
	0.20	K	±100	10~1M		
	Standard	±200	1.1M~10M	E24	J(±5%)	
		.,	+500~-200	1.0~9.1		
		K	±100	10~1M	F04.00	D(±1%), F(±1%)
		Standard	±200	1.02M~10M	E24, 96	, , , ,
RMGW35	0.33	1/	+500~-200	1~9.76		F(±1%)
1400000 0.000		K	±100	10~1M	E04	I/+E0/\
		Standard -	±200	1.1M~10M	E24	J(±5%)
			+500~-200	1.0~9.1		<u> </u>

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Table-1(2)

iable-i(2)						
Style	Rated dissipation (W)		ture coefficient of nce (10°/°C)	Rated resistance range (Ω)	Preferred number series for resistors	Tolerance on rated resistance
		K	±100	10~1M		D(140/) E(140/)
		Standard	±200	1.02M~10M	E24, 96	D(±1%), F(±1%)
DMOMEO	0.75	Stariuaru	+500~-200	1~9.76		F(±1%)
RMGW50	0.75	K	±100	10~1M		
		Standard	±200	1.1M~10M	E24	J(±5%)
		Otalidald	+500~-200	1.0~9.1		
		K	±100	10~1M		D(140/) E(140/)
		Standard	±200	1.02M~10M	E24, 96	D(±1%), F(±1%)
DMCMca	4	Stariuaru	+500~-200	1~9.76		F(±1%)
RMGW63	1	K	±100	10~1M		
		Standard	±200	1.1M~10M	E24	J(±5%)
		Sandard	+500~-200	1.0~9.1		

Table-1(3)

			,
Style	Limiting element voltage	Isolation voltage (V)	Category temperature range(°C)
	(*/	(-)	range(e)
RMGW06	25	50	
RMGW10	50	100	
RMGW16	50	100	
RMGW20	150		−55~+155
RMGW32			-55~+155
RMGW35	200	500	
RMGW50	200		
RMGW63			

3.2 Chip Jumper

Table-1(4)

Style	Chip jumper	Resistance value of	Rated current of chip jumper
	symbol	chip jumper	(A)
RMGW06			1
RMGW10			1
RMGW16			1
RMGW20	in.	50.0	2
RMGW32	JP	50mΩmax.	2
RMGW35			2
RMGW50			2
RMGW63			2

3.3 Climatic category

55/155/56 Lower category temperature -55 °C

Upper category temperature +155 °C

Duration of the damp heat, steady state test 56days

3.4 Stability class

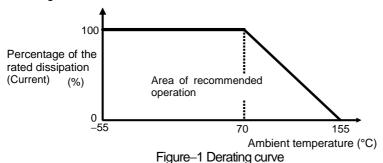
5% Limits for change of resistance:

-for long-term tests $\pm (2\% + 0.1\Omega)$ Chip jumper: 50 mΩ max. -for short-term tests $\pm (0.5\% + 0.05\Omega)$ Chip jumper: 50 mΩ max. RMGW-K-HTS-0001

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3.5 Derating

The derated values of dissipation (or current rating in case of chip jumper) at temperature in excess of 70 °C shall be as indicated by the following curve.



3.6 Rated voltage

d. c. or a. c. r. m. s. voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

Limiting element voltage can only be applied to resistors when the resistance value is equal to or higher than the critical resistance value.

At high value of resistance, the rated voltage may not be applicable.

4. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

Symbol	Packaging form		Standard packaging quantity / units	Application
В	Bulk (loose package)		1,000 pcs.	RMGW16,20,32,35,50,63
PA	Press pocket taping (paper taping)	8mm width, 2mm pitches	15,000 pcs.	RMGW06
TH	Paper taping	8mm width, 2mm pitches	10,000 pcs.	RMGW10
TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.	RMGW16,20,32
TE Embossed taping		8mm width, 4mm pitches	4.000 pag	RMGW35
16	Embossed taping	12mm width, 4mm pitches	4,000 pcs.	RMGW50,63

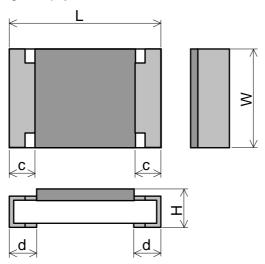
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5. Dimensions

5.1 The resistor shall be of the design and physical dimensions in accordance with Figure-2 and Table-3.



Figure–2 Table–3

Unit: mm Style W Н С d RMGW06 0.6 ± 0.03 0.3 ± 0.03 0.23 ± 0.03 0.15 ± 0.10 0.15±0.05 RMGW10 1.0±0.05 0.5 ± 0.05 0.35±0.05 0.2 ± 0.1 $0.25^{+0.05}_{-0.10}$ 0.8 +0.15 -0.05 RMGW16 1.6±0.1 0.45±0.10 0.3 ± 0.1 0.3±0.1 RMGW20 2.0±0.1 1.25±0.10 0.55±0.10 0.4±0.2 0.4±0.2 RMGW32 3.1±0.1 1.6±0.15 0.55±0.10 0.5±0.25 0.5±0.25 RMGW35 3.1±0.15 2.5±0.15 0.55±0.15 0.5±0.25 0.5 ± 0.25 RMGW50 5.0±0.15 2.5±0.15 0.55±0.15 0.6 ± 0.2 0.6 ± 0.2 RMGW63 0.6 ± 0.2 6.3±0.15 3.2 ± 0.15 0.55±0.15 0.6 ± 0.2

5.2 Net weight (Reference)

	,
Style	Net weight(mg)
RMGW06	0.16
RMGW10	0.6
RMGW16	2
RMGW20	5
RMGW32	9
RMGW35	16
RMGW50	25
RMGW63	40



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6. Marking

The Rated resistance of ,RMGW06, 10 should not be marked.

6.1 Resistor

The Rated resistance shall be marked in 3 digits (E24) or 4 digits (E96) and marked on over coat side.

• E24 series: 3 digits, E96 series: 4 digits

In case of the resistance value that E96 overlaps with E24, It is marked by either.

The Rated resistance of RMGW16 should not be marked in 4 digits(E96).

Marking example	Contents	Application
123	12x10 ³ $[\Omega] \rightarrow$ 12 $[k\Omega]$	E24(RMGW16,20,32,35,50,63)
2R2	2.2 [Ω]	E24(RMGW16,20,32,35,50,63)
5623	$562 \times 10^{\circ} [\Omega] \rightarrow 562 [k\Omega]$	E96(RMGW20,32,35,50,63)
12R7	12.7 [Ω]	E96(RMGW20,32,35,50,63)

6.2 Marking example of Jumper Chip

Marking example	Contents	Application
0	JP	RMGW16,20,32
000	JP	RMGW35,50,63



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7. Performance

7.1 The standard condition for tests shall be in accordance with Sub-clause 4.2, JIS C 5201–1: 2011.

7.2 The performance shall be satisfied in Table-4.

Table-4(1)

No.	Test items	Test items Condition of test (JIS C 5201–1) Performance requirements		
1	Visual examination	Sub-clause 4.4.1	As in 4.4.1	
'	VISUAI EXALTIII IALION	Checked by visual examination.	The marking shall be legible, as	
		Checked by visual examination.	checked by visual examination.	
2	Dimension	Sub-clause 4.4.2	As specified in Table-3 of this	
-	Diricion	Sub-clause 4.4.2	specification.	
	Resistance	Sub-clause 4.5	As in 4.5.2	
		Cub Gladoc 4.0	The resistance value shall correspon	
			with the rated resistance taking into	
			account the specified tolerance.	
			Chip jumper: $50 \text{m}\Omega$ max.	
3	Voltage proof	Sub-clause 4.7		
		Method: 4.6.1.4	No breakdown or flash over	
		Test voltage: Alternating voltage with a peak		
		value of 1.42 times the		
		insulation voltage.		
		Duration: 60 s ± 5 s	B: 400	
		Insulation resistance	R≥1GΩ	
		Test voltage: Insulation voltage Duration: 1 min.		
4	Solderability	Sub-clause 4.17	As in 4.17.4.5	
-	Golderability	Without ageing	The terminations shall be covered with	
		Flux: The resistors shall be immersed in a	a smooth and bright solder coating.	
		non-activated soldering flux for 2s.		
		Bath temperature: 235 °C ± 5 °C		
		Immersion time: $2 s \pm 0.5 s$		
5	Mounting	Sub-clause 4.31		
		Substrate material: Epoxide woven glass		
	Overload (**)	Sub-clause 4.13		
	(in the mounted state)	The applied voltage shall be 2.5 times the		
		rated voltage or twice the limiting element		
		voltage, whichever is the less severe. Duration: 2 s		
		Visual examination	No visible damage	
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$	
			Chip jumper: $50m\Omega$ max.	
	Solvent resistance of the	Sub-clause 4.30	Legible marking	
	marking	Solvent: 2-propanol		
		Solvent temperature: 23 °C ± 5 °C		
		Method 1		
		Rubbing material: cotton wool		
		Without recovery		

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Table 4(2)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
6	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass	
	Bound strength of the end face plating	Sub-clause 4.33 Bent value: 3 mm (3225 size max.) 1 mm (5025 siz min.) Resistance	$\Delta R \le \pm (0.5\% + 0.05\Omega)$
	Final measurements	Sub-clause 4.33.6 Visual examination	Chip jumper: 50mΩ max. No visible damage
7	Resistance to soldering heat	Sub-clause 4.18 Solder temperature: 260 °C ± 5 °C Immersion time: 10 s ± 0.5 s Visual examination Resistance	As in 4.18.3.4 No sign of damage such as cracks. $\Delta R \le \pm (0.5\% + 0.05\Omega)$ Chip jumper: 50mΩ max.
	Component solvent resistance	Sub-clause 4.29 Solvent: 2-propanol Solvent temperature: 23 °C ± 5 °C Method 2 Recovery: 48 h Visual examination Resistance	No visible damage $\Delta R \le \pm (0.5\% + 0.05\Omega)$ Chip jumper: $50m\Omega$ max.
8	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass	
	Adhesion Rapid change temperature	Sub-clause 4.32 Force: 5 N (RMGW06: 3N) Duration: 10 s ± 1 s Visual examination Sub-clause 4.19 Lower category temperature: -55 °C Upper category temperature: +155 °C	No visible damage
		Duration of exposure at each temperature: 30 min. Number of cycles: 5 cycles. Visual examination Resistance	No visible damage $\Delta R \leq \pm (0.5\% + 0.05\Omega)$ Chip jumper: $50 m\Omega$ max.

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Table 4(3)

1able-4(3)						
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements			
9	Climatic sequence	Sub-clause 4.23				
	-Dry heat	Sub-clause 4.23.2				
		Test temperature: +155 °C				
		Duration: 16 h				
	-Damp heat, cycle	Sub-clause 4.23.3				
	(12+12hour cycle)	Test method: 2				
	First cycle	Test temperature: 55 °C				
		[Severity(2)]				
	-Cold	Sub-clause 4.23.4				
		Test temperature –55 °C				
		Duration: 2h				
	-Damp heat, cycle	Sub-clause 4.23.6				
	(12+12hour cycle)	Test method: 2				
	Remaining cycle	Test temperature: 55 °C				
		[Severity (2)]				
	D.C. Israel	Number of cycles: 5 cycles				
	–D.C. load	Sub-clause 4.23.7				
		The applied voltage shall be the rated voltage				
		or the limiting element voltage whichever is				
		the smaller.				
		Duration: 1 min. Visual examination	No visible damage			
		Resistance	$\Delta R \leq \pm (2\% + 0.1\Omega)$			
		1 Nesisial Ice	Chip jumper: $50 \text{m}\Omega$ max.			
10	Mounting	Sub-clause 4.31				
	-	Substrate material: Epoxide woven glass				
		(RMGW63 may use Alumina substrate.)				
	Endurance at 70 °C	Sub-clause 4.25.1				
		Ambient temperature: 70 °C ± 2 °C				
		Duration: 1000 h				
		The voltage shall be applied in cycles of 1.5 h				
		on and 0.5 h off.				
		The applied voltage shall be the rated voltage				
		or the limiting element voltage whichever is the smaller.				
		Examination at 48 h , 500 h and 1000 h:				
		Visual examination	No visible damage			
		Resistance	$\Delta R \le \pm (2\% + 0.1\Omega)$			
		1 COOLINE TO	Chip jumper: $50m\Omega$ max.			
11	Mounting	Sub-clause 4.31	C. up Janipon Contact Hox			
1	- · · · · · · · · · · · · · · · · · · ·	Substrate material: Epoxide woven glass				
	Variation of resistance with	Sub-clause 4.8	As in Table–1			
	temperature	_55 °C / +20 °C				
		+20 °C/+155°C				
			•			

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Table-4(4)

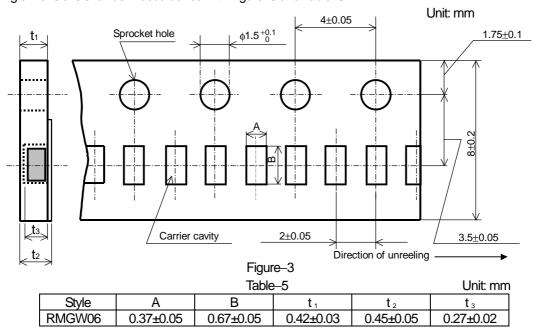
	Table 4(4)						
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements				
12	Mounting	Sub-clause 4.31					
		Substrate material: Epoxide woven glass					
	Damp heat, steady state	Sub-clause 4.24					
		Ambient temperature: 40 °C ± 2 °C					
		Relative humidity: 93 $^{+2}_{-3}$ %					
		a) 1st group: without voltage applied.					
		b) 2nd group: The d. c. voltage shall be					
		applied continuously.					
		The voltage shall be accordance with					
	Sub-clause 4.24.2.1 b). without po						
	voltage [4.24.2.1, c)]		No visible demons				
		Visual examination	No visible damage				
			Legible marking				
		Resistance	$\Delta R \le \pm (2\% + 0.1\Omega)$				
40	5: (1.63)		Chip jumper: 50mΩ max.				
13	Dimensions (detail)	Sub-clause 4.4.3	As in Table–3				
	Mounting	y inting					
	Mounting Sub-clause 4.31						
		Substrate material: Epoxide woven glass					
	Endurance at upper category Sub-clause 4.25.3						
	temperature	Ambient temperature:155 °C ± 2 °C					
	Duration: 1000 h						
	Examination at 48 h, 500 h and						
	1000 h:						
		Visual examination	No visible damage				
		Resistance	$\Delta R \le \pm (2\% + 0.1\Omega)$				
			Chip jumper: 50mΩ max.				
14	Humid Sulfur vapor test	ASTM B809					
	(FOS)	Reagent: Sulfur (Saturated vapor)					
		Test temp.: 60°C					
		Relative humidity: 95%RH					
		Test period: 1000h					
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$				
			Chip jumper: $50m\Omega$ max.				

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8. Taping

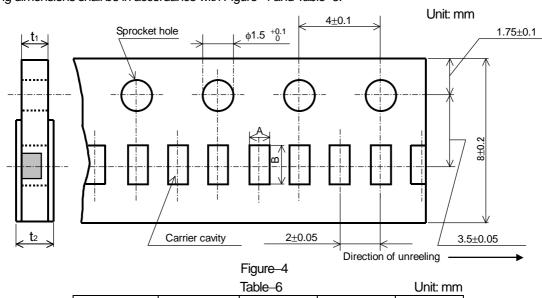
- 8.1 Applicable documents JIS C 0806-3: 2014, EIAJ ET-7200C: 2010
- 8.2 Taping dimensions
- 9.2.1 Press pocket taping (Paper taping, 8mm width, 2mm pitches)

Taping dimensions shall be in accordance with Figure-3 and Table-5.



8.2.2 Paper taping (8mm width, 2mm pitches)

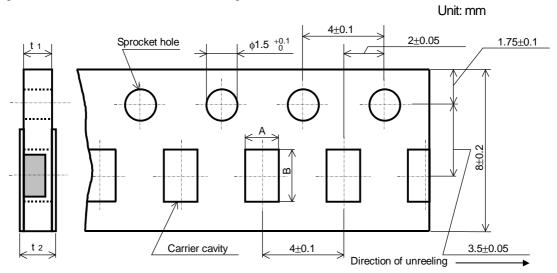
Taping dimensions shall be in accordance with Figure-4 and Table-6.



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8.2.3 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-5 and Table-7.



Figure–5
Table–7
Unit: mm

A B t₁ t₂

1.15±0.15 1.9±0.2 0.6±0.1 0.8max.

1.65±0.15 2.5±0.2 0.8±0.1 1.0max.

 0.8 ± 0.1

1.0max.

 3.6 ± 0.2

8.2.3 Embossed taping dimensions shall be in accordance with Figure-6 and Table-8.

2.00±0.15

Style

RMGW16

RMGW20

RMGW32

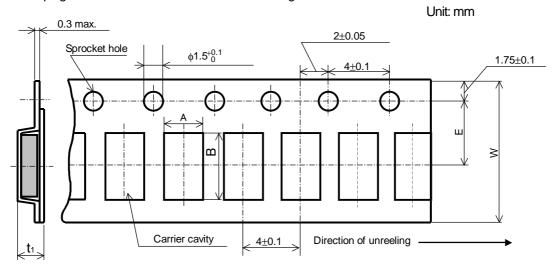


Figure-6
Table-8
Unit: mm
Style A B W E t 1

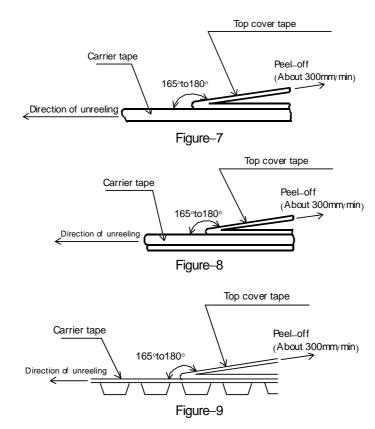
Style	A	D	VV		l 1
RMGW35	2.85±0.20	3.5±0.2	8.0±0.3	3.5±0.05	1.0±0.2
RMGW50	3.1±0.2	5.5±0.2	12.0±0.3	5.5±0.05	1.1±0.15
RMGW63	3.6±0.2	6.9±0.2	12.0±0.3	5.5±0.05	1.1±0.15

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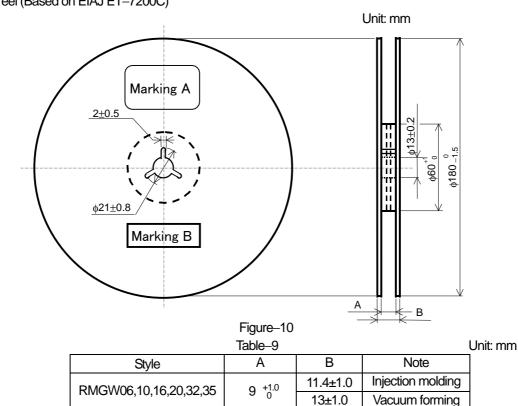
- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following RMGW06: Figure–7. RMGW10,16,20,32: Figure–8 and RMGW35,50,63 Figure-9.
- 6). When the tape is bent with the minimum radius for 25 mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- In no case shall there be two or more consecutive components missing.
 The maximum number of missing components shall be one or 0.1%, whichever is greater.
- 8). The resistors shall be faced to upward at the over coating side in the carrier cavity.



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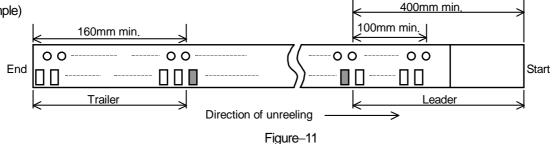
8.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure–10 and Table–9. Plastic reel (Based on EIAJ ET–7200C)



Note: Marking label shall be marked on a place of Marking A or two place of marking A and B.

8.4 Leader and trailer tape.(Example)



13 ^{+1.0}

17±1.0

Vacuum forming

9. Marking on package

The label of a minimum package shall be legibly marked with follows.

RMGW50,63

9.1 Marking A

(1) Classification

(Style, Temperature coefficient of resistance, Rated resistance, Tolerance on rated resistance, Packaging form)

(2) Quantity (3) Lot number (4) Manufacturer's name or trade mark (5) Others

9.2 Marking B (KAMAYA Control label)